

PETG Basic

• Basic Info

Bambu **PETG Basic** is specially optimized to minimize oozing, stringing, and clumping during printing, effectively addressing most common issues found in regular PETG in the market. It offers PETG's features of impact and water resistance, flexibility, strong layer adhesion, and durability. Ideal for printing tools (vises, tensioners, bag clips), toys (frisbees, boomerangs), water containers (bottles, watering cans), and outdoor items (planter pots, bottle cages) that require long-term exposure and withstanding impacts.

• Specifications

Subjects	Data
Diameter	1.75 mm
Net Filament Weight	1 kg
Spool Material	ABS (Temperature resistance 70 °C)
Spool Size	Diameter: 200 mm; Height: 67 mm

• Recommended Printing Settings

Subjects	Data
Drying Settings before Printing	65 °C, 8 h
Printing and Storage Humidity	< 20% RH (Sealed, with desiccant)
Nozzle Temperature	240 - 270 °C
Bed Type	Engineering Plate, High Temperature Plate or Textured PEI Plate
Nozzle Size	0.4, 0.6, 0.8 mm
Bed Surface Preparation	Glue
Bed Temperature	65 - 75 °C
Cooling Fan	0 - 60%
Printing Speed	< 200 mm/s
Retraction Length	0.8 - 1.4 mm
Retraction Speed	30 - 60 mm/s
Chamber Temperature	35 - 50 °C

Subjects	Data
Max Overhang Angle	~ 70 °
Max Bridging Length	~30 mm
Support Material	Turn On

• Properties

Bambu Lab has tested the differing aspects in the performance of PETG Basic material, including physical, mechanical, and chemical properties. Typical values are listed as followed:

Physical Properties			
Subjects	Testing Methods	Data	
Density	ISO 1183	1.25 g/cm ³	
Melt Index	210 °C, 2.16 kg	18.6 ± 2.2 g/10 min	
Melting Temperature	DSC, 10 °C/min	225 °C	
Glass Transition Temperature	DSC, 10 °C/min	68 °C	
Crystallization Temperature	DSC, 10 °C/min	N / A	
Vicat Softening Temperature	ISO 306, GB/T 1633	78 °C	
Heat Deflection Temperature	ISO 75 1.8 MPa	65 °C	
Heat Deflection Temperature	ISO 75 0.45 MPa	69 °C	
Saturated Water Absorption Rate	25 °C, 55% RH	0.32%	

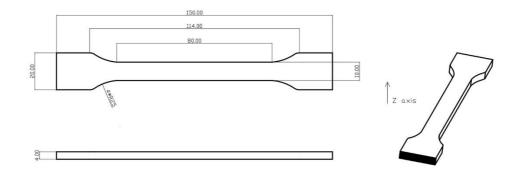
Mechanical Properties		
Subjects	Testing Methods	Data
Young's Modulus (X-Y)	ISO 527, GB/T 1040	1460 ± 190 MPa
Young's Modulus (Z)	ISO 527, GB/T 1040	1120 ± 130 MPa
Tensile Strength (X-Y)	ISO 527, GB/T 1040	48 ± 5 MPa
Tensile Strength (Z)	ISO 527, GB/T 1040	39 ± 3 MPa
Breaking Elongation Rate (X-Y)	ISO 527, GB/T 1040	11.2 ± 0.8 %
Breaking Elongation Rate (Z)	ISO 527, GB/T 1040	5.7 ± 0.6 %
Bending Modulus (X-Y)	ISO 178, GB/T 9341	1790 ± 120 MPa
Bending Modulus (Z)	ISO 178, GB/T 9341	1580 ± 130 MPa
Bending Strength (X-Y)	ISO 178, GB/T 9341	81 ± 4 MPa
Bending Strength (Z)	ISO 178, GB/T 9341	64 ± 3 MPa
Impact Strength (X-Y)	ISO 179, GB/T 1043	52.7 ± 2.4 kJ/m ² ; 21.6 ± 1.8 kJ/m ² (notched)
Impact Strength (Z)	ISO 179, GB/T 1043	$13.6 \pm 0.8 \text{ kJ/m}^2$

Other Physical and Chemical Properties		
Subjects	Data	
Odor	Odorless	
Composition	PETG	
Skin Hazards	No hazard	
Chemical Stability	Stable under normal storage and handling conditions	
Solubility	Insoluble in water	
Resistance to Acid	Not resistant	
Resistance to Alkali	Not resistant	
Resistance to Organic Solvent	Not resistant to some organic solvents	
Resistance to Oil and Grease	Resistant to most kinds of oil and grease	
Flammability	Flammable and self-extinguishing in the air	
Combustion Products	Water, carbon oxides	
Odor of Combustion Products	Odorless	

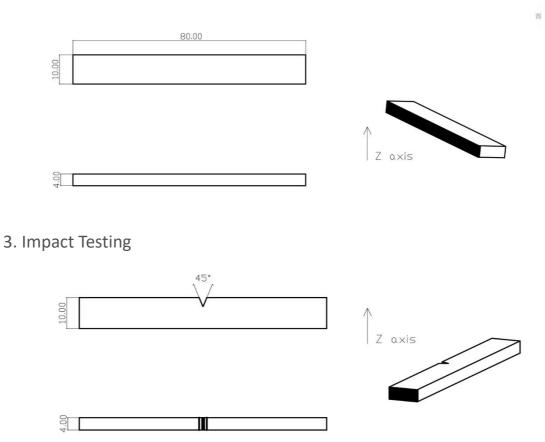
• Specimen Test

Specimen Printing Conditions		
Subjects	Data	
Nozzle Temperature	255 °C	
Bed Temperature	70 °C	
Printing Speed	150 mm/s	
Infill Density	100%	
*All the specimens were annealed and dried at 65 °C for 8 hours before testing.		

1. Tensile Testing



2. Bending Testing



• Disclaimer

The performance values are tested by standard samples at Bambu Lab, and the values are for design reference and comparison only. Actual 3D printing model performance is related to many other factors, including printers, printing conditions, printing models, printing parameters, etc.

In the process of using Bambu Lab 3D printing filaments, users are responsible for the legality, safety, and performance indicators of printing. Bambu Lab is not responsible for the use of materials and scenarios and is not responsible for any damage that occurs in the process of using our filaments.